

FEATURES

- Available as "HR" (high reliability) screened per MIL-PRF-19500, JANTX level. Add "HR" suffix to base part number.
- Available as non-RoHS (Sn/Pb plating), standard, and as RoHS by adding "-PBF" suffix.

MAXIMUM RATINGS

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	90	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_J = 150^\circ\text{C}$)	I_D	$T_C = 25^\circ\text{C}$	A
		$T_C = 100^\circ\text{C}$	
Pulse Drain Current ¹	I_{DM}	3	
Maximum Power Dissipation	P_D	$T_C = 25^\circ\text{C}$	W
		$T_A = 25^\circ\text{C}$	
Thermal Resistance, Junction to Ambient	R_{thJA}	170	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Case	R_{thJC}	20	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

Note 1: Pulse width limited by maximum junction temperature

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Limits			Unit	
			Min	Typ ²	Max		
STATIC							
Drain-Source Breakdown Voltage	V_{DS}	$V_{DS} = 0\text{V}, I_D = 10\mu\text{A}$	90	125	-	V	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 1\text{mA}$		0.8	1.6	2	V
			$T_A = -55^\circ\text{C}$	-	1.8	2.5	
			$T_A = 125^\circ\text{C}$	0.3	1.3	-	
Gate-Body Leakage	I_{GSS}	$V_{GS} = \pm 20\text{V}$	$V_{DS} = 0\text{V}$	-	-	± 100	nA
			$T_A = 125^\circ\text{C}$	-	-	± 500	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS} = 0\text{V}$	$V_{DS} = 72\text{V}$	-	-	1	μA
			$T_A = 125^\circ\text{C}$	-	-	100	μA
On-State Drain Current ²	$I_{D(on)}$	$V_{GS} = 10\text{V}$	$V_{DS} = 10\text{V}$	-	1.8	-	mA
Drain-Source On-State Resistance ²	$R_{DS(on)}$	$V_{GS} = 5\text{V}$	$I_D = 0.3\text{A}$	-	3.8	5.3	Ω
			$I_D = 1\text{A}$	-	3.6	4	
				$T_A = 125^\circ\text{C}$	-	6.7	
Forward Transconductance ²	g_{fs}	$V_{DS} = 7.5\text{V}, I_D = 0.475\text{A}$		170	340	-	mS
Diode Forward Voltage	V_{SD}	$V_{GS} = 0\text{V}, I_S = 0.86\text{A}$		0.7	0.9	1.4	V
DYNAMIC							
Input Capacitance	C_{iss}	$V_{GS} = 0\text{V}$	$V_{DS} = 25\text{V}, f = 1\text{MHz}$	-	35	50	pF
Output Capacitance	C_{oss}			-	15	40	
Reverse Transfer Capacitance	C_{rss}			-	2	10	
Drain Source Capacitance	C_{ds}			-	30	-	

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90V N-CHANNEL MOSFET

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise specified)

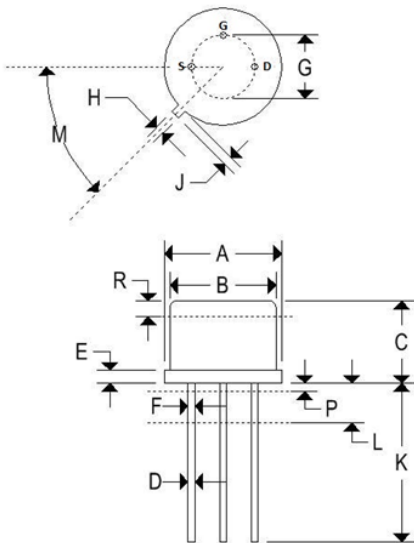
Parameter	Symbol	Test Conditions	Limits			Unit
			Min	Typ	Max	
SWITCHING ³						
Turn-On Time	t_{ON}	$V_{DD} = 25\text{V}, R_L = 23\ \Omega, I_D \approx 1\text{A},$ $V_{GEN} = 10\text{V}, R_g = 23\ \Omega$	-	6	10	nS
Turn-Off Time	t_{OFF}		-	8	10	

Note 2. Pulse test: $PW \leq 300\ \mu\text{s}$ duty cycle $\leq 2\%$.

Note 3. Switching time is essentially independent of operating temperature.

MECHANICAL CHARACTERISTICS

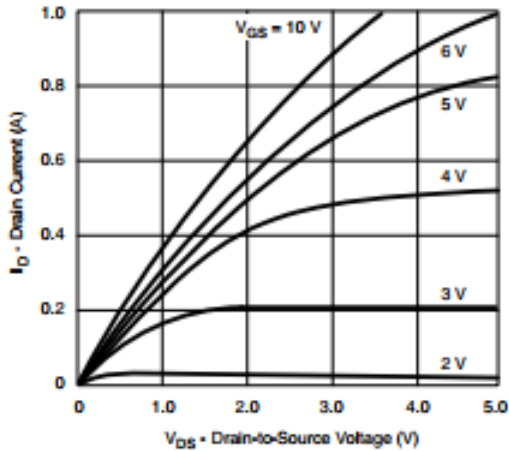
Case	TO-39
Marking	Alpha-numeric
Pin out	See below



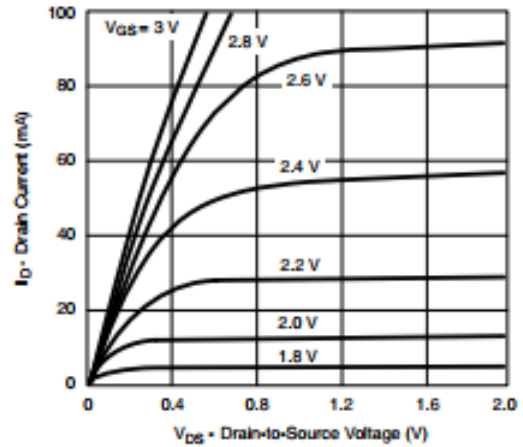
	TO-39			
	Inches		Millimeters	
	Min	Max	Min	Max
A	0.350	0.370	8.890	9.400
B	0.315	0.335	8.000	8.510
C	0.240	0.260	6.10	6.60
D	0.016	0.021	0.406	0.533
E	0.009	0.125	0.2269	3.180
F	0.016	0.019	0.406	0.533
G	0.190	0.210	4.830	5.33
H	0.028	0.034	0.711	0.864
J	0.029	0.040	0.737	1.020
K	0.500	-	12.700	-
L	0.250	-	6.350	-
M	45° NOM		45° NOM	
P	-	0.050	-	1.270
Q	90° NOM		90° NOM	
R	0.100	-	2.540	-

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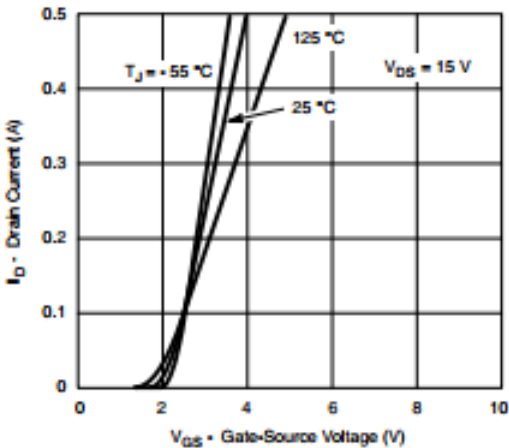
90V N-CHANNEL MOSFET



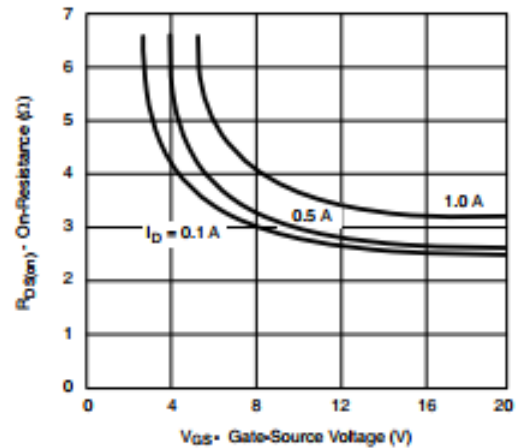
Ohmic Region Characteristics



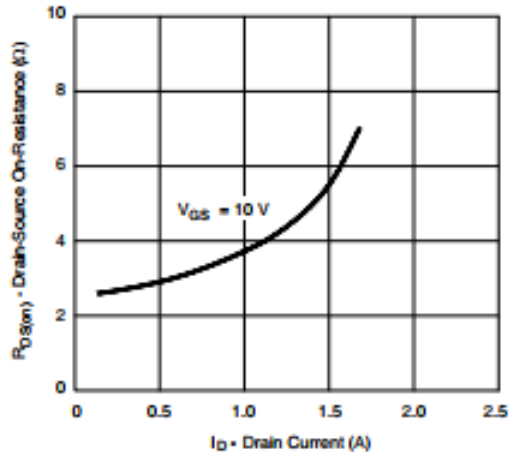
Output Characteristics for Low Gate Drive



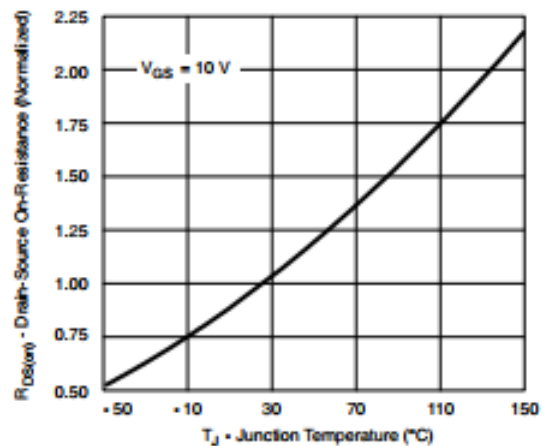
Transfer Characteristics



On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Drain Current



Normalized On-Resistance vs. Junction Temperature

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